FAIRCHILD SEMICONDUCTOR®

July 2011

FDC8602

Dual N-Channel PowerTrench® MOSFET

100 V, 1.2 A, 350 mΩ

Features

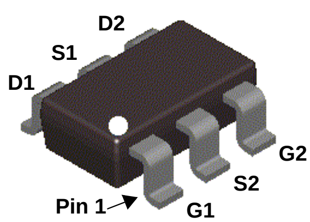
- Max $r_{DS(on)}$ = 350 mΩ at V_{GS} = 10 V, I_D = 1.2 A
- Max $r_{DS(on)}$ = 575 mΩ at V_{GS} = 6 V, I_D = 0.9 A
- High performance trench technology for extremely low $r_{DS(on)}$
- High power and current handling capability in a widely used surface mount package
- Fast switching speed
- 100% UIL Tested
- RoHS Compliant

General Description

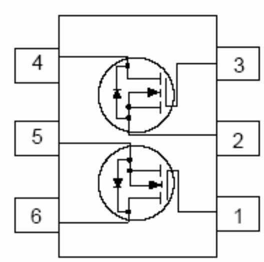
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Applications

- Load Switch
- Synchronous Rectifier



SuperSOT™ -6



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	100	V
V_{GS}	Gate to Source Voltage	±20	V
I_D	Drain Current -Continuous (Note 1a)	1.2	A
	-Pulsed	5	A
E_{AS}	Single Pulse Avalanche Energy (Note 3)	1.5	mJ
P_D	Power Dissipation (Note 1a)	0.96	W
	Power Dissipation (Note 1b)	0.69	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	60	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	130	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.862	FDC8602	SSOT-6	7 ”	8 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units

Off Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250 µA, V_{GS} = 0 V	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 µA, referenced to 25 °C		73		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 80 V, V_{GS} = 0 V			1	µA
I_{GSS}	Gate to Source Leakage Current	V_{GS} = ±20 V, V_{DS} = 0 V			±100	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
$V_{GS(th)}$	Gate to Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 250 µA	2	3.2	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 µA, referenced to 25 °C		-8		mV/°C
$r_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 1.2 A		285	350	mΩ
		V_{GS} = 6 V, I_D = 0.9 A		409	575	
		V_{GS} = 10 V, I_D = 1.2 A, T_J = 125 °C		489	600	
g_{FS}	Forward Transconductance	V_{DS} = 10 V, I_D = 1.2 A		1.3		S

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
C_{iss}	Input Capacitance	V_{DS} = 50 V, V_{GS} = 0 V, f = 1MHz		53	70	pF
C_{oss}	Output Capacitance			17	25	pF
C_{rss}	Reverse Transfer Capacitance			0.8	5	pF
R_g	Gate Resistance			1.6		Ω

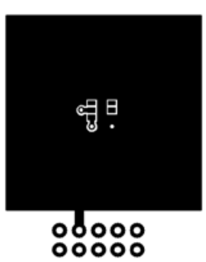
Switching Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 50 V, I_D = 1.2 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		3.5	10	ns
t_r	Rise Time			1.7	10	ns
$t_{d(off)}$	Turn-Off Delay Time			5.4	11	ns
t_f	Fall Time			2.3	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V_{GS} = 0 V to 10 V; V_{DD} = 50 V, I_D = 1.2 A		1.2	2	nC
$Q_{g(TOT)}$	Total Gate Charge	V_{GS} = 0 V to 5 V; V_{DD} = 50 V, I_D = 1.2 A		0.6	1	nC
Q_{gs}	Gate to Source Charge	V_{DD} = 50 V, I_D = 1.2 A		0.4		nC
Q_{gd}	Gate to Drain "Miller" Charge			0.4		nC

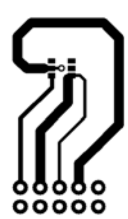
Drain-Source Diode Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
V_{SD}	Source-Drain Diode Forward Voltage	V_{GS} = 0 V, I_S = 1.2 A (Note 2)		0.86	1.3	V
t_{rr}	Reverse Recovery Time	I_F = 1.2 A, di/dt = 100 A/µs		27	43	ns
Q_{rr}	Reverse Recovery Charge			12	21	nC

NOTES:
1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 130 °C/W when mounted on a 1 in^2 pad of 2 oz copper



b) 180 °C/W when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < 300 µs, Duty cycle < 2.0%.

3. Starting T_J = 25 °C; N-ch: L = 3 mH, I_{AS} = 1 A, V_{DD} = 100 V, V_{GS} = 10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

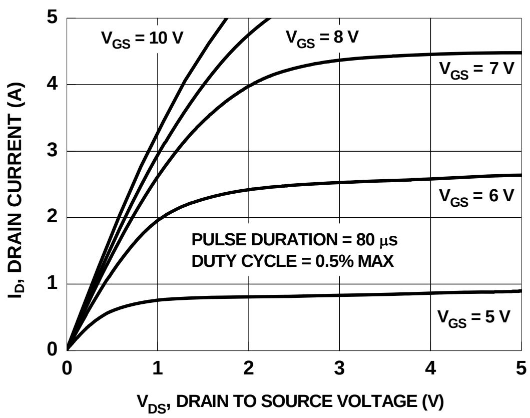


Figure 1. On Region Characteristics

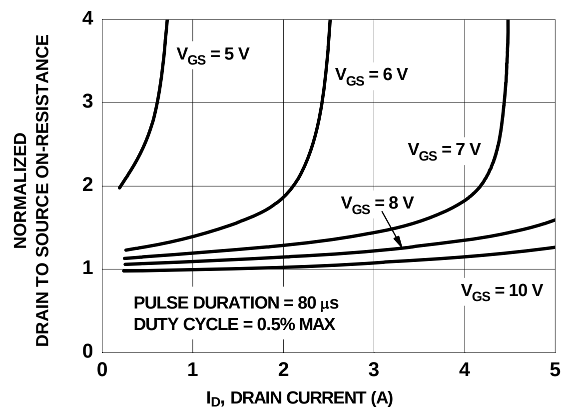


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

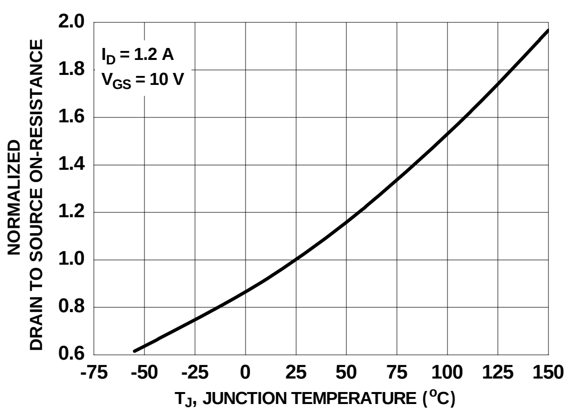


Figure 3. Normalized On Resistance vs Junction Temperature

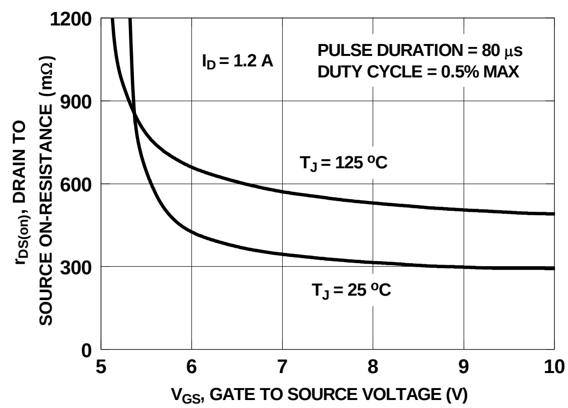


Figure 4. On-Resistance vs Gate to Source Voltage

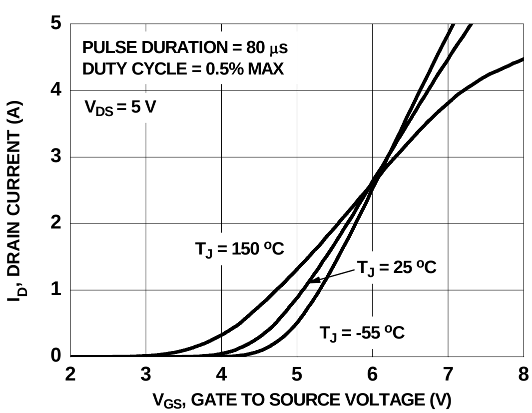


Figure 5. Transfer Characteristics

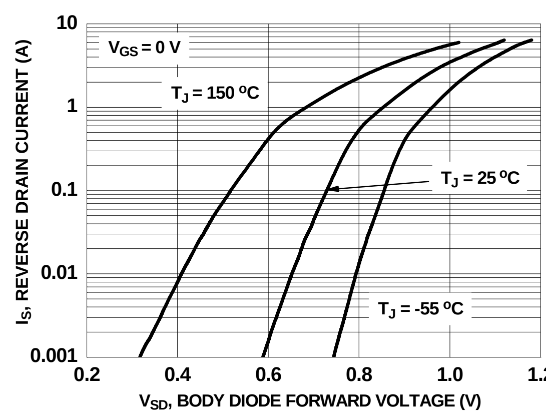


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted

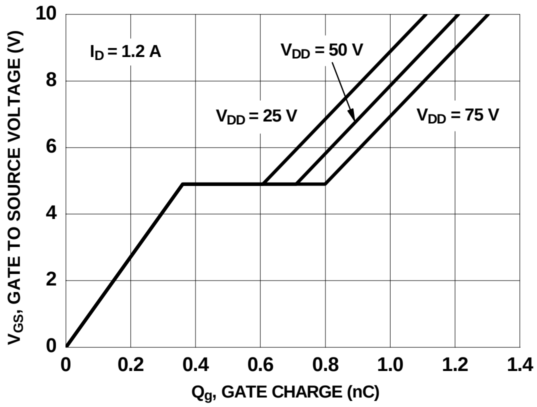


Figure 7. Gate Charge Characteristics

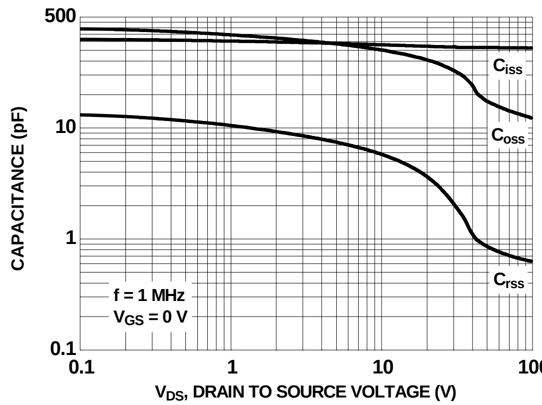


Figure 8. Capacitance vs Drain to Source Voltage

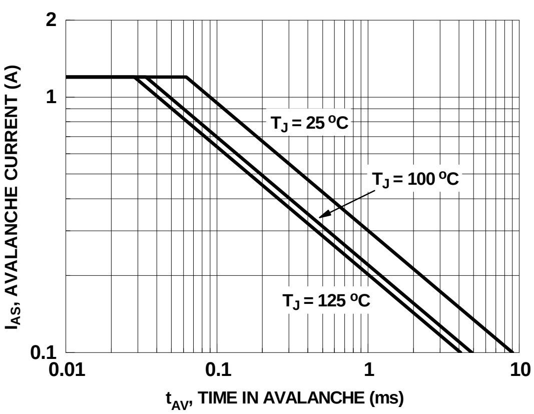


Figure 9. Unclamped Inductive Switching Capability

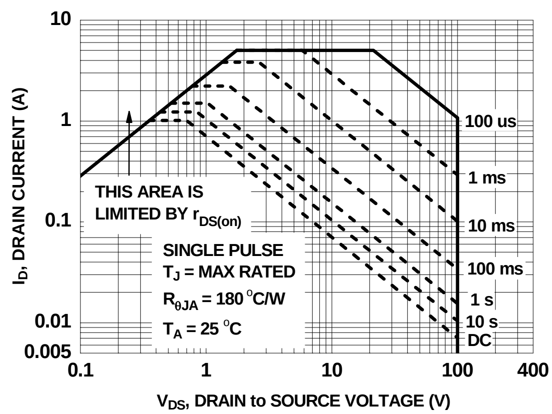


Figure 10. Forward Bias Safe Operating Area

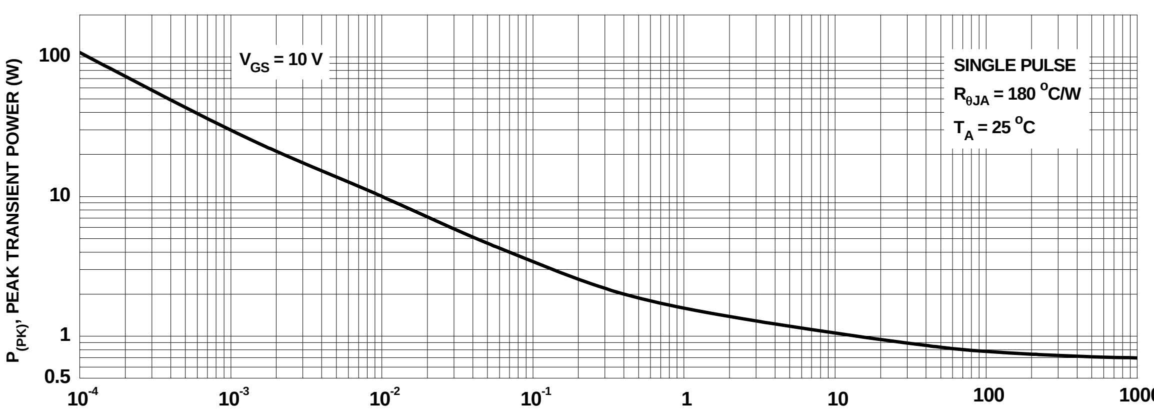


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

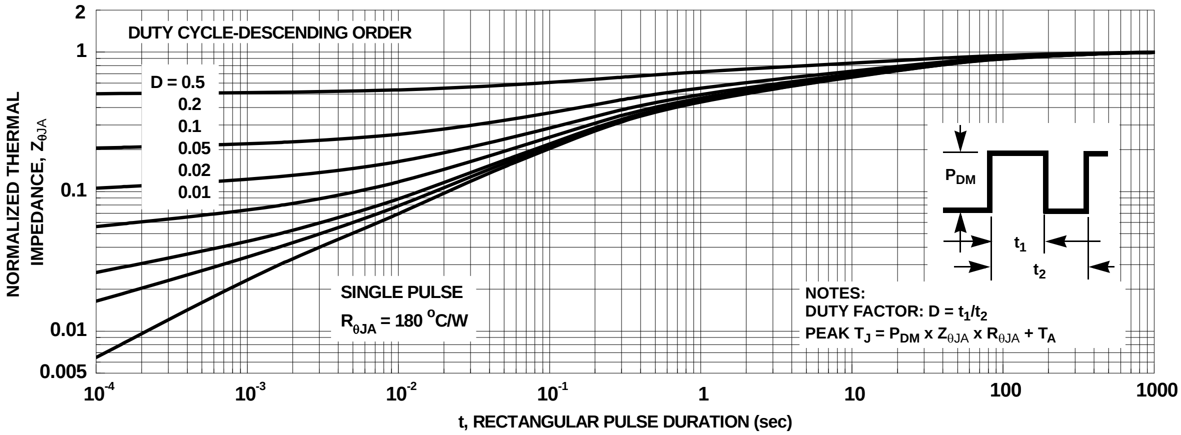
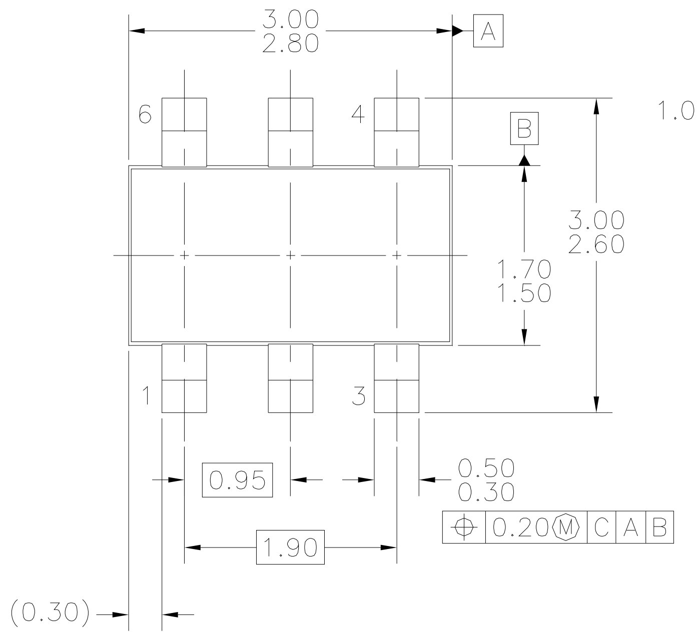
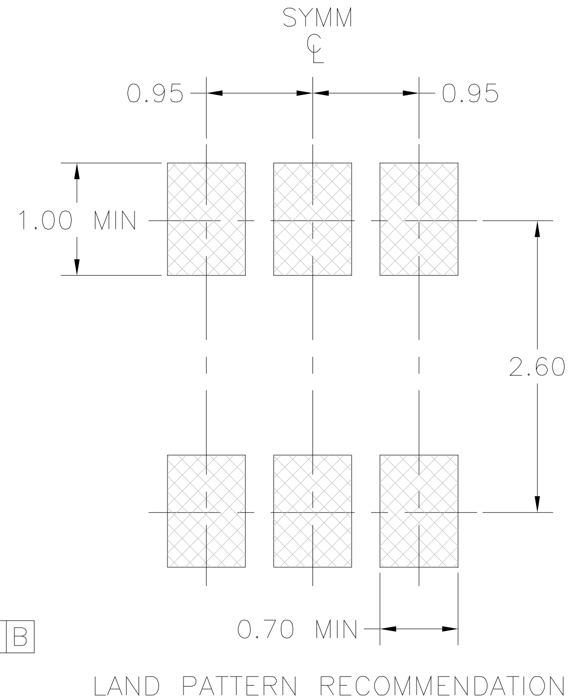
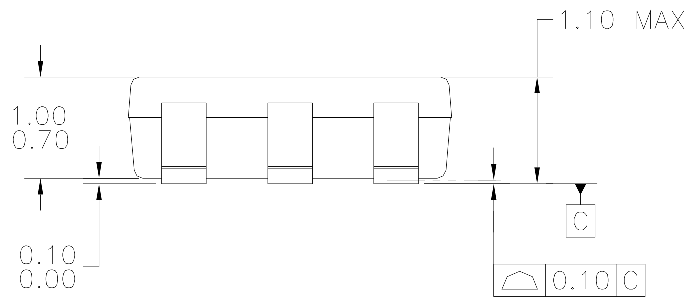


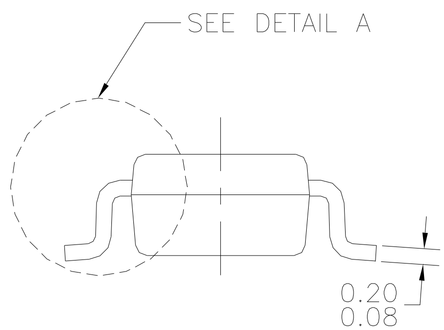
Figure 12. Junction-to-Ambient Transient Thermal Response Curve

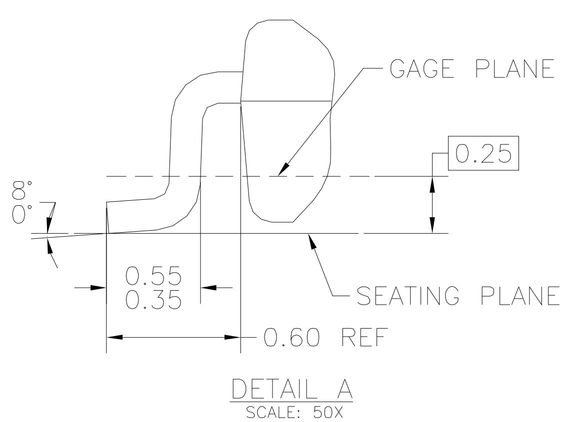
Dimensional Outline and Pad Layout











NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO JEDEC MO-193. VAR. AA, ISSUE C, DATED JANUARY 2000.

B) ALL DIMENSIONS ARE IN MILLIMETERS.

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